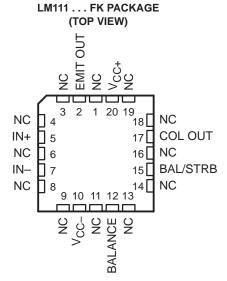
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- Fast Response Times
- Strobe Capability
- Maximum Input Bias Current . . . 300 nA
- Maximum Input Offset Current . . . 70 nA

LM111 ... JG PACKAGE LM211 . . . D, P, OR PW PACKAGE LM311 . . . D, P, PS, OR PW PACKAGE (TOP VIEW) **EMIT OUT** $II V_{CC+}$ T COL OUT IN+ 2 7 6 ∏ BAL/STRB IN-3 BALANCE 5 Λ^{CC^-}

- Can Operate From Single 5-V Supply
- Available in Q-Temp Automotive
 - High-Reliability Automotive Applications
 - Configuration Control/Print Support
 - Qualification to Automotive Standards



NC - No internal connection

description/ordering information

The LM111, LM211, and LM311 are single high-speed voltage comparators. These devices are designed to operate from a wide range of power-supply voltages, including ± 15 -V supplies for operational amplifiers and 5-V supplies for logic systems. The output levels are compatible with most TTL and MOS circuits. These comparators are capable of driving lamps or relays and switching voltages up to 50 V at 50 mA. All inputs and outputs can be isolated from system ground. The outputs can drive loads referenced to ground, V_{CC+} or V_{CC-} . Offset balancing and strobe capabilities are available, and the outputs can be wire-OR connected. If the strobe is low, the output is in the off state, regardless of the differential input.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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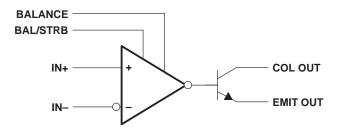
description/ordering information

ORDERING INFORMATION

TA	V _{IO} max AT 25°C	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
		PDIP (P)	Tube of 50	LM311P	LM311P	
		COIC (D)	Tube of 75	LM311D	LM311	
−0°C to 70°C	7.5 mV	SOIC (D)	Reel of 2500	LM311DR	LIVISTI	
-0 0 10 70 0	7.51110	SOP (PS)	Reel of 2000	LM311PSR	L311	
		T000D (DIA)	Reel of 150	LM311PW	L311	
	TSSOP (PW)		Tube of 2000	LM311PWR	LSII	
	3 mV	PDIP (P)	Tube of 50	LM211P	LM211P	
		SOIC (D)	Tube of 75	LM211D	LM211	
–40°C to 85°C			Reel of 2500	LM211DR	LIVIZ I I	
		TSSOP (PW)	Reel of 150	LM211PW	L211	
		1330F (FW)	Reel of 2000	LM211PWR	LZII	
-40°C to 125°C	3 mV	SOIC (D)	Tube of 75	LM211QD	LM211Q	
-40 C to 125°C		3010 (D)	Reel of 2500	LM211QDR	LIVIZTIQ	
–55°C to 125°C	3 mV	CDIP (JG)	Tube of 50	LM111JG	LM111JG	
-55 C to 125°C	SIIIV	LCCC (FK) Tube of 55		LM111FK	LM111FK	

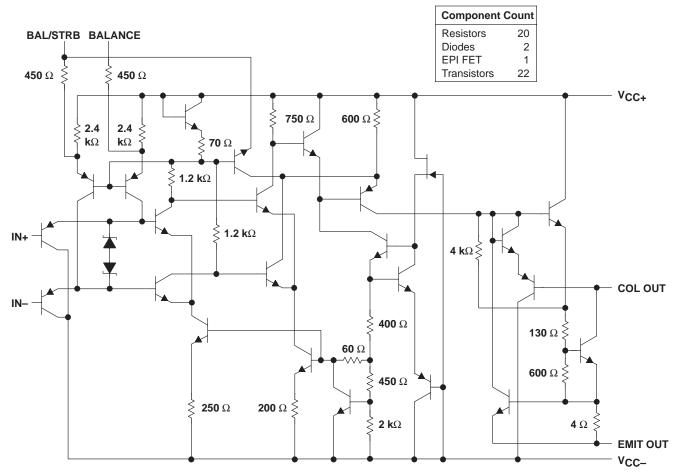
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

functional block diagram





schematic



All resistor values shown are nominal.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage: V _{CC+} (see Note 1)	18 V
V _{CC} – (see Note 1)	
V _{CC+} - V _{CC-}	36 V
Differential input voltage, V _{ID} (see Note 2)	
Input voltage, V _I (either input, see Notes 1 and 3)	
Voltage from emitter output to V _{CC}	
Voltage from collector output to V _{CC} -: LM111	
	50 V
	50 V
	40 V
Duration of output short circuit (see Note 4)	
Package thermal impedance, θ_{JA} (see Notes 5 and 6): D p	
	ackage 85°C/W
	package 95°C/W
	/ package 149°C/W
Package thermal impedance, θ_{JC} (see Notes 7 and 8): FK	
	package 14.5°C/W
Operating virtual junction temperature, T _J	
Case temperature for 60 seconds: FK package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 second	
Lead temperature 1,6 mm (1/16 inch) from case for 60 second	
Storage temperature range, T _{stq}	
5 , 3tg	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. Differential voltages are at IN+ with respect to IN-.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or ±15 V, whichever is less.
 - 4. The output may be shorted to ground or either power supply.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

			MIN	MAX	UNIT
VCC+-VCC-	Supply voltage		3.5	30	V
VI	Input voltage ($ V_{CC\pm} \le 15 \text{ V}$)		V _{CC} _+0.5	V _{CC+} -1.5	V
		LM111	- 55	125	°C
T.	Oncreting free pir temperature range	LM211	-40	85	
T _A	Operating free-air temperature range	LM211Q	-40	125	C
		LM311	0	70	



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electrical characteristics at specified free-air temperature, $V_{\text{CC}\pm}$ = ± 15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A †		LM111 LM211 LM211Q		LM311			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIO	Input offset voltage	See Note 6		25°C		0.7	3		2	7.5	mV
V10	input onset voltage	See Note o		Full range			4			10	111 V
lio	Input offset current	See Note 6		25°C		4	10		6	50	nA
10	mpat onoot ourront	000 11010 0		Full range			20			70	
I _{IB}	Input bias current	V _O = 1 V to 14 V		25°C		75	100		100	250	nA
,ID	·	10 110111		Full range			150			300	
I _{IL(S)}	Low-level strobe current (see Note 7)	V _(strobe) = 0.3 V,	$V_{ID} \le -10 \text{ mV}$	25°C		-3			-3		mA
VICR	Common-mode input voltage range			Full range	13 to –14.5	13.8 to –14.7		13 to –14.5	13.8 to –14.7		V
A _{VD}	Large-signal differential voltage amplification	$V_0 = 5 \text{ V to } 35 \text{ V},$	R _L = 1 kΩ	25°C	40	200		40	200		V/mV
	High-level	$I_{\text{(strobe)}} = -3 \text{ mA},$	V _{OH} = 35 V,	25°C		0.2	10				nA
ІОН	(collector) output leakage	V _{ID} = 5 mV		Full range			0.5				μΑ
	current	$V_{ID} = 5 \text{ mV},$	V _{OH} = 35 V	25°C					0.2	50	nA
	Low-level (collector-to-emitter) output voltage $V_{CC+} = 4.5 \text{ V}, V_{CC-} = 0, I_{OI} = 8 \text{ mA}$	I- 50 A	$V_{ID} = -5 \text{ mV}$	25°C		0.75	1.5				
		IOT = 20 mV	$V_{ID} = -10 \text{ mV}$	25°C					0.75	1.5	
VOL			$V_{ID} = -6 \text{ mV}$	Full range		0.23	0.4				V
		VCC-= 0, I _{OL} = 8 mA	V _{ID} = -10 mV	Full range					0.23	0.4	
I _{CC+}	Supply current from V _{CC+} , output low	$V_{ID} = -10 \text{ mV},$	No load	25°C		5.1	6		5.1	7.5	mA
ICC-	Supply current from V _{CC} , output high	V _{ID} = 10 mV,	No load	25°C		-4.1	– 5		-4.1	-5	mA

[†] Unless otherwise noted, all characteristics are measured with BALANCE and BAL/STRB open and EMIT OUT grounded.

switching characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C

PARAMETER		LM111 LM211 LM211Q LM311	UNIT		
				1115	
Response time, low-to-high-level output	$R_{\rm C} = 500 \Omega$ to 5 V,	$C_1 = 5 pF$	See Note 8	115	ns
Response time, high-to-low-level output	1 KC = 300 22 10 3	CL = 5 pr,	See Note o	165	ns

NOTE 11: The response time specified is for a 100-mV input step with 5-mV overdrive and is the interval between the input step function and the instant when the output crosses 1.4 V.



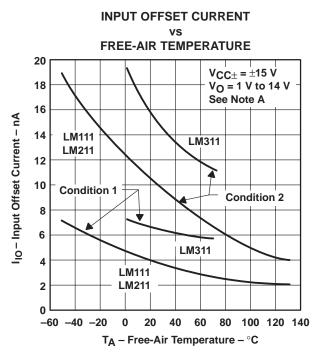
Full range for LM111 is -55°C to 125°C, for LM211 is -40°C to 85°C, for LM211Q is -40°C to 125°C, and for LM311 is 0°C to 70°C.

[‡] All typical values are at $T_A = 25$ °C.

NOTES: 9. The offset voltages and offset currents given are the maximum values required to drive the collector output up to 14 V or down to 1 V with a pullup resistor of 7.5 kΩ to V_{CC+}. These parameters actually define an error band and take into account the worst-case effects of voltage gain and input impedance.

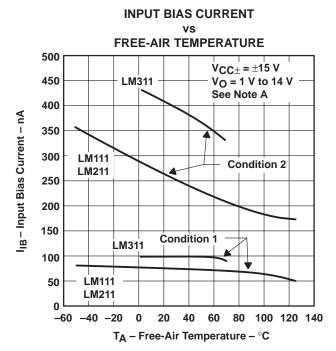
^{10.} The strobe should not be shorted to ground; it should be current driven at -3 mA to -5 mA (see Figures 13 and 27).

TYPICAL CHARACTERISTICS[†]



NOTE A: Condition 1 is with BALANCE and BAL/STRB open. Condition 2 is with BALANCE and BAL/STRB connected to V_{CC+} .

Figure 1



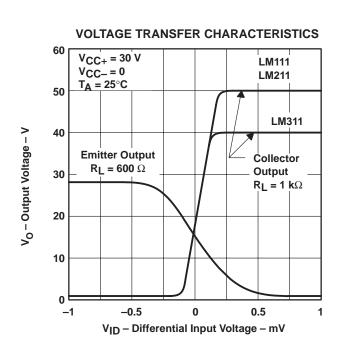
NOTE A: Condition 1 is with BALANCE and BAL/STRB open. Condition 2 is with BALANCE and BAL/STRB connected to VCC+.

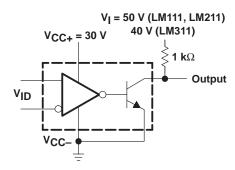
Figure 2

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

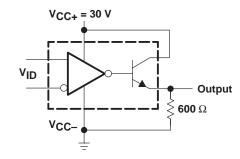


TYPICAL CHARACTERISTICS[†]





COLLECTOR OUTPUT TRANSFER CHARACTERISTIC TEST CIRCUIT FOR FIGURE 3



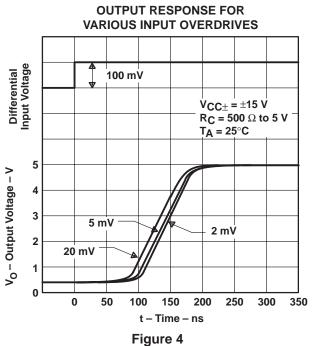
EMITTER OUTPUT TRANSFER CHARACTERISTIC TEST CIRCUIT FOR FIGURE 3

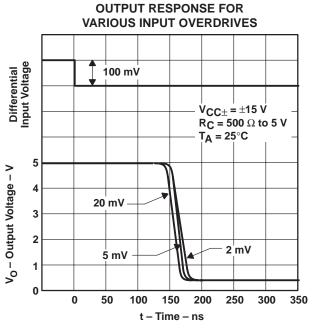
Figure 3

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

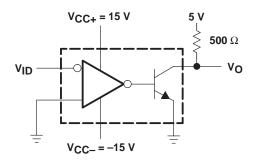


TYPICAL CHARACTERISTICS



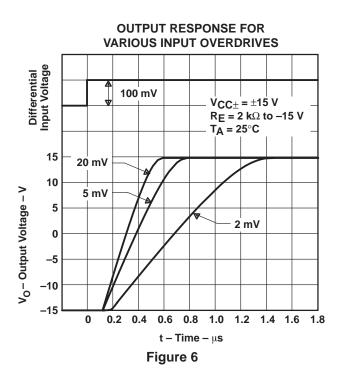


4 Figure 5



TEST CIRCUIT FOR FIGURES 4 AND 5

TYPICAL CHARACTERISTICS



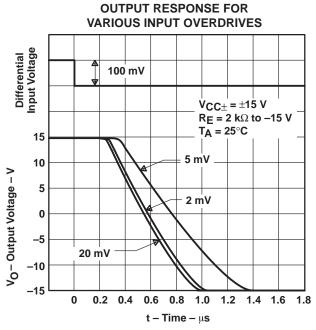
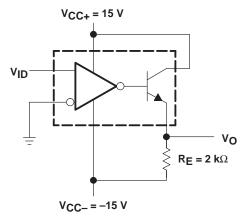
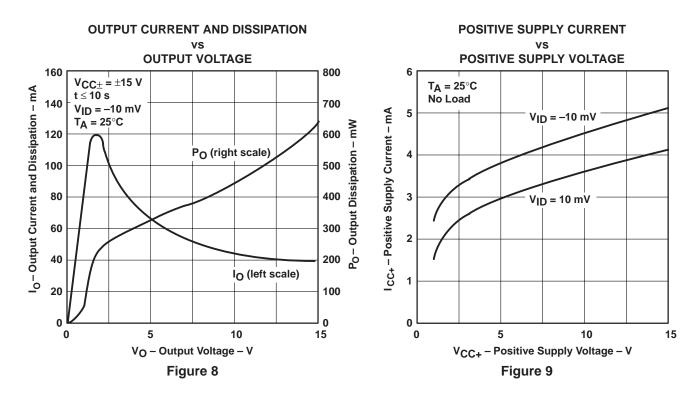


Figure 7



TEST CIRCUIT FOR FIGURES 6 AND 7

TYPICAL CHARACTERISTICS



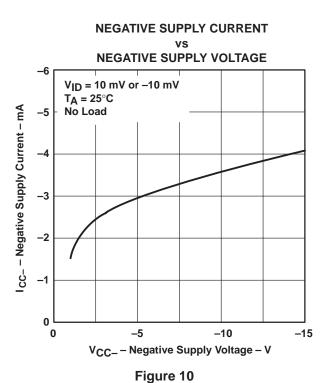




Figure 11 through Figure 29 show various applications for the LM111, LM211, and LM311 comparators.

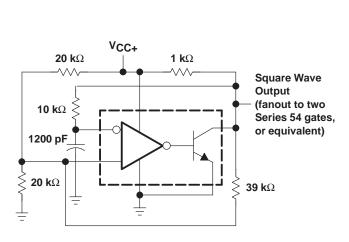
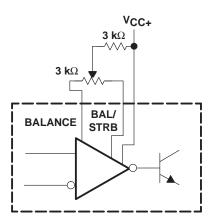


Figure 11. 100-kHz Free-Running Multivibrator



NOTE: If offset balancing is not used, the BALANCE and BAL/STRB pins should be shorted together.

Figure 12. Offset Balancing

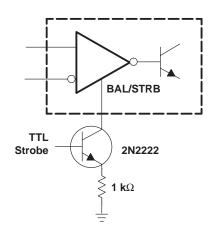


Figure 13. Strobing

NOTE: Do not connect strobe pin directly to ground, because the output is turned off whenever current is pulled from the strobe pin.

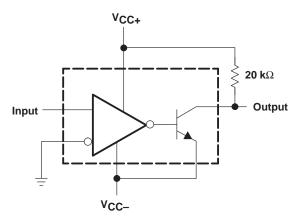
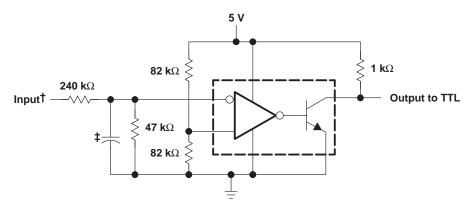
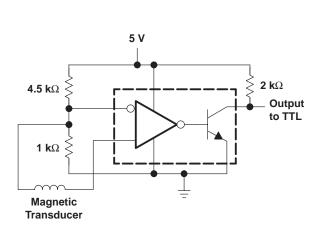


Figure 14. Zero-Crossing Detector



- † Resistor values shown are for a 0- to 30-V logic swing and a 15-V threshold.
- ‡ May be added to control speed and reduce susceptibility to noise spikes

Figure 15. TTL Interface With High-Level Logic





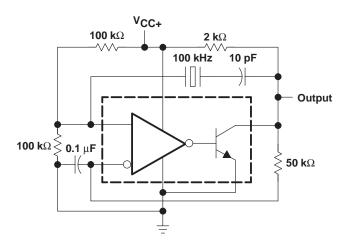


Figure 17. 100-kHz Crystal Oscillator

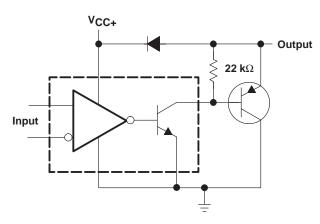
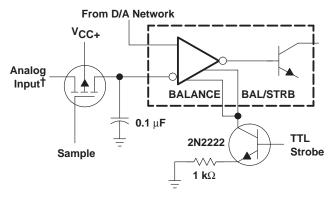


Figure 18. Comparator and Solenoid Driver



† Typical input current is 50 pA with inputs strobed off.

Figure 19. Strobing Both Input and Output Stages Simultaneously

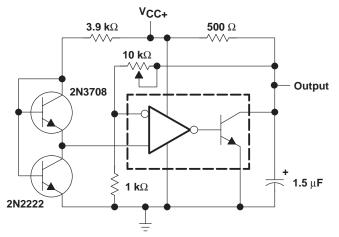


Figure 20. Low-Voltage Adjustable Reference Supply

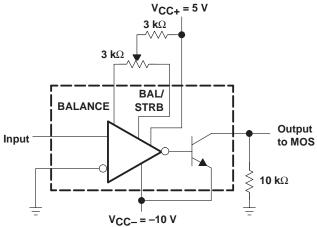
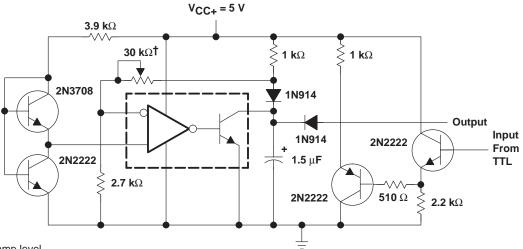


Figure 21. Zero-Crossing Detector Driving MOS Logic



† Adjust to set clamp level

Figure 22. Precision Squarer

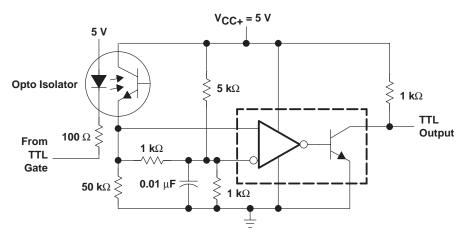


Figure 23. Digital Transmission Isolator

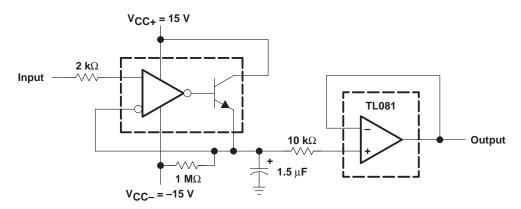


Figure 24. Positive-Peak Detector



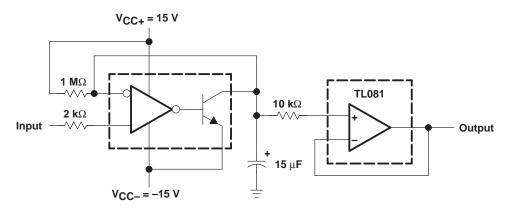
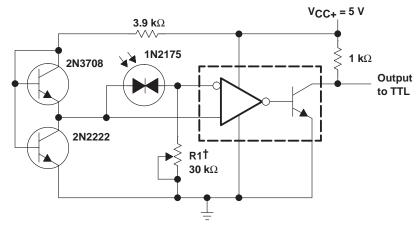
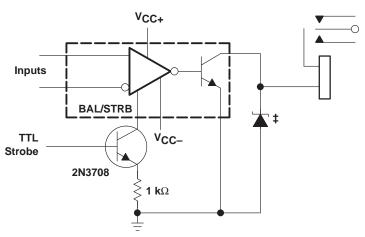


Figure 25. Negative-Peak Detector



†R1 sets the comparison level. At comparison, the photodiode has less than 5 mV across it, decreasing dark current by an order of magnitude.

Figure 26. Precision Photodiode Comparator



[‡] Transient voltage and inductive kickback protection

Figure 27. Relay Driver With Strobe



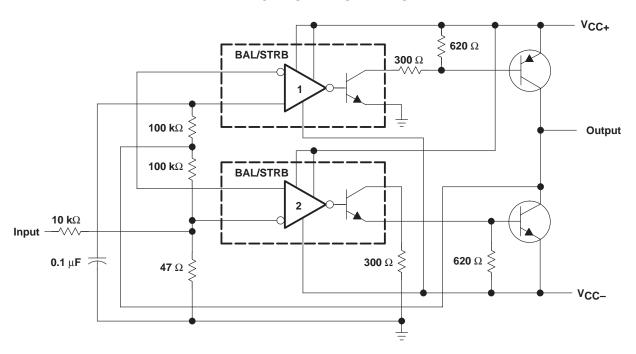


Figure 28. Switching Power Amplifier

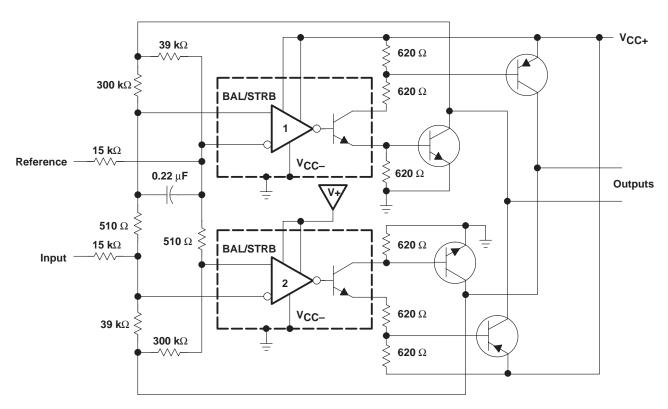


Figure 29. Switching Power Amplifiers









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
JM38510/10304BPA	ACTIVE	CDIP	JG	8	1	None	A42 SNPB	Level-NC-NC-NC
LM111FKB	ACTIVE	LCCC	FK	20	1	None	POST-PLATE	Level-NC-NC-NC
LM111JG	ACTIVE	CDIP	JG	8	1	None	A42 SNPB	Level-NC-NC-NC
LM111JGB	ACTIVE	CDIP	JG	8	1	None	A42 SNPB	Level-NC-NC-NC
LM211D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM211DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM211P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
LM211PW	ACTIVE	TSSOP	PW	8	150	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
LM211PWR	ACTIVE	TSSOP	PW	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
LM211QD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM211QDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM311D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM311DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
LM311PSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM311PW	ACTIVE	TSSOP	PW	8	150	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
LM311PWLE	OBSOLETE	TSSOP	PW	8		None	Call TI	Call TI
LM311PWR	ACTIVE	TSSOP	PW	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
LM311Y	OBSOLETE	XCEPT	Υ	0		None	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder



PACKAGE OPTION ADDENDUM

25-Feb-2005

temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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